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Technical Data:

Thermally Conductive Silicone Interface Pad: HWP-080

Product Features:

- -Good thermal conductivity
- -High conformability and cost effective
- -Shock absorbing and naturally tacky
- -Electrically insulating

-it is easy to fill in air gaps between PC board and heat sinks or a metal chassis

Product Applications:

- Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink.
- Led Lighting, LCD TV, Telecom device, wireless Hub,NB, PC, power supply etc
- Cooling Module, Thermal module, in all applications where a metal housing is used as heatsink.

Product description:

Typical Properties of HWP-080 Pad			
Properties	Units	HWP080	Test Method
Construction & Composition		Silicone & Ceramic filled	
Color		Gray	Visual
Thickness Range	mm	0.5~12.0	
Hardness	Shore C	18 or 35	ASTM D224
Density	g/cc	2	ASTM D792
Tensile Strength	KN/m	1.3	ASTM D412
Elongation	%	1.35	ASTM D412
Continuous Use Temp	°C	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥4.0	ASTM D149
Volume Impedance	ohm-cm	1.7*10 ¹⁶	ASTM D257
Dielectric Constant	1MHz	4.51	ASTM D150
Weight Daminify		≤1 %	@150°C 240
Flame Rating		V0	UL 94
Thermal Conductivity	W/m.k	0.8	ASTM D547
UL, RoHS, REACH		Compliance	

